

Figure 6 shows formation of a conductor pattern including a circuit pattern upon the insulation film for formation of an LGA package of comparatively large size.

Figure 7 is a magnified drawing of a part of FIG. 6.

Figure 8 is a flow chart showing manufacturing steps for a semiconductor package according to the present invention.

Figure 9 are side views corresponding to each of the steps of FIG. 8.

Figure 10 shows a pattern structure upon thermoplastic insulation film of conventional construction used for production of a semiconductor package.

10 REFERENCE NUMERALS AND SYMBOLS AS SHOWN IN THE FIGURES

	p	pitch of through holes
	L	pitch of sprocket holes
	10	insulation film
15	12	sprocket holes
	14	through holes
	16	circuit pattern
	18	for-plating-use conductor pattern
	20	main line
20	22	sub-line
	90	semiconductor chip
	92	conductor wire
	94	molding
	96	solder bump
25	98	through hole
	100	dicing blade
	102	sprocket hole
	104	dicing table